PCN Number:		20200609000.1						Date:		2, 2020			
Title: Qualification of CDAT as a device					as an	addition	al assembly site	& Bu	ımp	site f	or select \	WCSP	
Customer Contact: PCN Manager			nager	<b>Dept:</b> Quality Services									
			ept 22	2, 2020	Estimated Sample Date provided at								
Cha	nge 1	Туре:		•							•	•	
$\boxtimes$	Asser	mbly Sit	e			Design			ite				
	Asser	mbly Pro	cess			☐ Data Sheet ☐ Wafer Bump Mater			aterial				
		mbly Ma				Part number change Wafer Bump Process							
		anical S				Test Site Wafer Fab Site							
Ш	Packi	ing/Ship	ping/Lab	eling		Test Process Wafer Fab Materia							
						-				Wafei	r Fab Proc	cess	
_						PCN	<b>Details</b>						
Des	cript	ion of C	hange:										
site	Texas Instruments is pleased to announce the qualification of CDAT as an additional assembly site & bump site for WCSP devices shown below. No material differences between sites.  Package Marking Difference:												
							Clark						
Marking Difference				11	Clark			TIC	DAT				
		Markir	ng Differ	ence		YM = YEAI	MS BA R MONTH DATE CODE EMBLY SITE CODE CE CODE	RC	S OW 2	YMS O F	ONTH DATE COBBLY SITE CODE		
Rea	son f	Markir		ence		YM = YEAI S = ASSI ROW 2 = DEVI	MS BA R MONTH DATE CODE EMBLY SITE CODE CE CODE	RO	S OW 2	YMS O F = YEAR N = ASSEM = DEVICE	ONTH DATE COBBLY SITE CODE		
			nge:	ence		YM = YEAI S = ASSI ROW 2 = DEVI	MS BA R MONTH DATE CODE EMBLY SITE CODE CE CODE	RO	S OW 2	YMS O F = YEAR N = ASSEM = DEVICE	ONTH DATE COBBLY SITE CODE		
Cont	tinuity	for Char	<b>nge:</b>		, Fit,	YM = YEAI S = ASSI ROW 2 = DEVI O = PIN	MS BA R MONTH DATE CODE EMBLY SITE CODE CE CODE		S OW 2 O	YMS O F = YEAR N = ASSEM = DEVICE = PIN A1	MONTH DATE CO BLY SITE CODE CODE		
Cont	tinuity i <b>cipat</b>	for Char	<b>nge:</b>		, Fit,	YM = YEAI S = ASSI ROW 2 = DEVI O = PIN	MS BA R MONTH DATE CODE EMBLY SITE CODE CE CODE A1		S OW 2 O	YMS O F = YEAR N = ASSEM = DEVICE = PIN A1	MONTH DATE CO BLY SITE CODE CODE		
Anti None Anti	tinuity icipat e icipat	for Char y of Sup ted imp	nge: ply act on F	Form	rial D	YM = YEAI S = ASSI ROW 2 = DEVI O = PIN Function	MS BA  R MONTH DATE CODE EMBLY SITE CODE CE CODE A1  , Quality or Re	liabi	s ow 2 o	YMS O F = YEAR N = ASSEM = DEVICE = PIN A1	MONTH DATE COBBLY SITE CODE	egative):	
Anti None Anti	tinuity icipat e icipat No I Mate	for Char y of Sup ted imp ted imp mpact to erial Dec	nge: ply act on f act on f the laration	Form Mate	rial Do Mat from prod repo	YM = YEAI S = ASSI ROW 2 = DEVI O = PIN  Function eclaratio erial Decl n product duction re orts can b	MS BA  R MONTH DATE CODE EMBLY SITE CODE CE CODE A1	uct C I be a oduct ie site	Sow 2 O	YMS O F  = YEAR M = ASSEM = DEVICE = PIN A1  / (pos tent re ilable 1 releas nk belo	itive / ne	egative):  driven the rised	

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
CLARK	QAB	PHL	Angeles City, Pampanga
CDAT	CDA	CHN	Chengdu

Sample product shipping label (not actual product label)



5A (L)T0:1750



(1P) \$N74L\$07N\$R (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483\$12 (P) (2P) REV: (V) 0033317

(2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS

## **Product Affected:**

TPS22916BYFPR TPS22916BYFPT

# **Qualification Report**

Approve Date 02-Jun-2020

### **Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TPS22916BYFP	QBS Product Reference: TPS22916BYFP	QBS Product Reference: TPS22916CYFP	QBS Process Reference: TPA6140A2YFF
ED	Electrical Characterization	Per Datasheet Parameters	-	Pass	Pass	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-
HBM	ESD - HBM	2500 V	1/3/0	-	1/3/0	-
CDM	ESD - CDM	1000 V	1/3/0	-	1/3/0	-
HTOL	Life Test, 125C	1000 Hours	-	-	-	-
HTOL	Life Test, 140C	480 Hours	-	-	-	3/231/0
HTOL	Life Test, 150C	300 Hours	-	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	-	-
LU	Latch-up	(per JESD78)	-	-	1/6/0	3/18/0
PD	Physical Dimensions		-	-	-	-
SBS	Solder Ball Shear		-	-	-	-
TC	Temperature Cycle -55/125C	700 Cycles	-	-	-	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	-	3/231/0	-
UHAS T	Unbiased HAST, 130C/85%RH	96 Hours	1/77/0	-	3/231/0	3/231/0

Туре	Test Name / Condition	Duration	QBS Process Reference: TPS62620YFF	QBS Process Reference: TPS65830YFF (JET)	QBS Package Reference: TPS2120YFPR
ED	Electrical	Per Datasheet	-	-	-
	Characterization	Parameters			
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0
HBM	ESD - HBM	2500 V	-	-	-
CDM	ESD - CDM	1000 V	-	-	-
HTOL	Life Test, 125C	1000 Hours	-	-	1/77/0
HTOL	Life Test, 140C	480 Hours	-	-	-
HTOL	Life Test, 150C	300 Hours	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	1/77/0
LU	Latch-up	(per JESD78)	3/18/0	318/0	-
PD	Physical Dimensions		-	-	-
SBS	Solder Ball Shear		-	-	-
TC	Temperature Cycle - 55/125C	700 Cycles	3/231/0	3/231/0	3/231/0
TC	Temperature Cycle, - 65/150C	500 Cycles	-	-	-
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0

- QBS: Qual By Similarity
- Qual Device TPS22916BYFP is qualified at LEVEL1-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at Tl's external Web site: http://www.ti.com/

#### Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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